

REMARKS

In view of the amendments proposed above, Applicants respectfully request consideration of the following remarks.

Anticipation Rejections Under 35 U.S.C. § 102

A claim is anticipated only if each and every element as set forth in the claim is found, either expressly or inherently described, in a single prior art reference. *Verdegaal Brothers v. Union Oil Co. of California*, 2 U.S.P.Q.2d 1051, 1053 (Fed. Cir. 1987). The identical invention must be shown in as complete detail as is contained in the claim. *Richardson v. Suzuki Motor Co.*, 9 U.S.P.Q.2d 1913, 1920 (Fed. Cir. 1989).

Anticipation Rejection Based on United States Patent 6,208,525 to Imasu et al.

Claims 1-17 and 31-33 were rejected under 35 U.S.C. § 102(b) as being anticipated by United States Patent 6,208,525 to Imasu et al. (hereinafter “Imasu”). Applicants respectfully traverse this rejection, as set forth below.

Claim 1, as amended, recites:

1. An apparatus comprising:
 - a conductive land disposed on a first component, the land having a **permanent** depression shaped to receive a conductive bump extending from a second component; and
 - a layer of a conductive material disposed over the land and the depression, the conductive material layer to form electrical contact with the conductive bump extending from the second component and into the depression.

Each of independent claims 7, 13, and 31 has been amended to include a limitation similar to independent claim 1.

Imasu discloses an electrode pad 4A having a recess 4B (See, e.g., FIGS. 2, 10, and 11 of this reference); however, this recess 4B is not permanent. As stated in Imasu, at column 5, line 62 to column 6, line 4 and column 7, lines 62-67 (emphasis added):

The recess 4B in the electrode pad 4A is formed by **elastic deformation** of the electrode pad 4A and the soft layer 3. The elastic deformation of the electrode pad 4A and the soft layer 3 occurs as a result that the bump electrode 15 is pressed to the electrode pad 4A by the pressure of the semiconductor chip 10 when this semiconductor chip 10 is mounted on the mounting face of the wiring board 1. As a result, the **elastic forces of the electrode pad 4A and the soft layer 3 act upon the bump electrode 15.**

* * * *

Even if the bump electrode 15 are moved upward by the expansion of the adhesive 16 in the thickness direction, moreover, **the depth of the recesses 4B changes following up the movement of the bump electrodes 15**, so that the connection between the electrode pads 4A and the bump electrodes 15 can be retained.

Therefore, as Imasu fails to disclose at least the above-noted limitations of independent claims 1, 7, 13, and 31, each of these claims is novel in view of Imasu. Also, claims 2-6, 8-12, 14-17, and 32-33 are allowable as depending from novel independent claims 1, 7, 13, and 31, respectively.

CONCLUSION

Applicants submit that claims 1-17 and 31-33 are in condition for allowance and respectfully request allowance of such claims.

Please charge any shortages and credit any overages to Deposit Account No. 02-2666.

Respectfully submitted,

Date: September 22, 2006

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